

COMBINATIONAL LOGIC DYNAMICS

[Adapted from Rabaey's *Digital Integrated Circuits*, ©2002, J. Rabaey et al.]

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Fast Complex Gates: Design Technique 1

- Transistor sizing
 - » as long as fan-out capacitance dominates
- Progressive sizing
 - » Distributed RC line
 - » $M1 > M2 > M3 > \dots > MN$
(the fet closest to the output is the smallest)
 - » Can reduce delay by more than 20%; decreasing gains as technology shrinks

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Fast Complex Gates: Design Technique 2

- Transistor ordering
 - » delay determined by time to discharge C_L , C_1 , and C_2
 - » delay determined by time to discharge C_L

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Fast Complex Gates: Design Technique 3

- Alternative logic structures
 - » $F = ABCDEFGH$
 - » Shows a large multi-input AND gate followed by an inverter, and a tree of smaller gates.

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Fast Complex Gates: Design Technique 4

- Isolating fan-in from fan-out using buffer insertion
 - » Shows a circuit with a buffer inserted between the fan-in and fan-out stages.

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Fast Complex Gates: Design Technique 5

- Reducing the voltage swing
 - » $t_{pHL} = 0.69 (3/4 (C_L V_{DD}) / I_{DSATn})$
 - » $= 0.69 (3/4 (C_L V_{swing}) / I_{DSATn})$
 - » linear reduction in delay
 - » also reduces power consumption
 - But the following gate is much slower!
 - Or requires use of "sense amplifiers" on the receiving end to restore the signal level (memory design)

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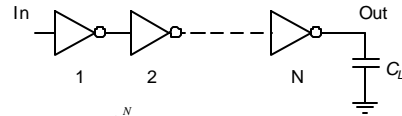
Sizing Logic Paths for Speed

- Frequently, input capacitance of a logic path is constrained
- Logic also has to drive some capacitance
- Example: ALU load in an Intel's microprocessor is 0.5pF
- How do we size the ALU datapath to achieve maximum speed?
- We have already solved this for the inverter chain – can we generalize it for any type of logic?

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Buffer Example



$$Delay = \sum_{i=1}^N (p_i + g_i \cdot f_i) \quad (\text{in units of } \tau_{inv})$$

For given N : $C_{i+1}/C_i = C/C_{i-1}$
 To find N : $C_{i+1}/C_i \sim 4$
 How to generalize this to any logic path?

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Logical Effort

$$Delay = k \cdot R_{unit} C_{unit} \left(1 + \frac{C_L}{g C_{in}} \right)$$

$$= t(p + g \cdot f)$$

p – intrinsic delay ($3kR_{unit}C_{unit}\gamma$) – gate parameter $\neq f(W)$
 g – logical effort ($kR_{unit}C_{unit}$) – gate parameter $\neq f(W)$
 f – effective fanout

Normalize everything to an inverter:
 $g_{inv} = 1, p_{inv} = 1$

Divide everything by τ_{inv}
 (everything is measured in unit delays τ_{inv})
 Assume $\gamma = 1$.

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Delay in a Logic Gate

Gate delay:

$$d = h + p$$

effort delay intrinsic delay

Effort delay:

$$h = g f$$

logical effort effective fanout = C_{out}/C_{in}

Logical effort is a function of topology, independent of sizing
 Effective fanout (electrical effort) is a function of load/gate size

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Logical Effort

- Inverter has the smallest logical effort and intrinsic delay of all static CMOS gates
- Logical effort of a gate presents the ratio of its input capacitance to the inverter capacitance when sized to deliver the same current
- Logical effort increases with the gate complexity

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Intrinsic Delay

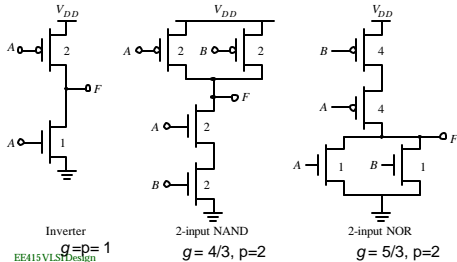
- Inverter has the smallest intrinsic delay and of all static CMOS gates
- Intrinsic delay of a gate presents the ratio of its output capacitance to the inverter output capacitance when sized to deliver the same current
- Intrinsic delay increases with the gate complexity

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Logical Effort

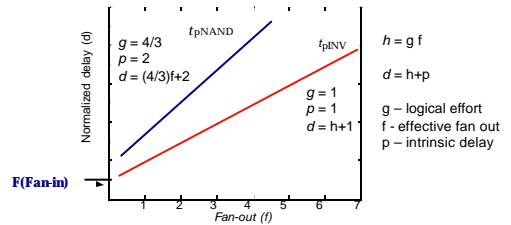
Logical effort is the ratio of input capacitance of a gate to the input capacitance of an inverter with the same output current



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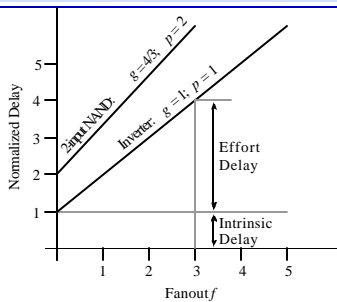
Logical Effort of Gates



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Logical Effort of Gates



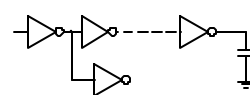
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Add Branching Effort

Branching effort: $C_{off-path}$ is the branch capacitance

$$b = \frac{C_{on-path} + C_{off-path}}{C_{on-path}}$$



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Multistage Networks

$$Delay = \sum_{i=1}^N (p_i + g_i \cdot f_i)$$

Stage effort: $h_i = g_i f_i$

Path electrical effort: $F = C_{out}/C_{in}$

Path logical effort: $G = g_1 g_2 \dots g_N$

Branching effort: $B = b_1 b_2 \dots b_N$

Path effort: $H = GFB$

Path delay $D = \sum d_i = \sum p_i + \sum h_i$

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Optimum Effort per Stage

When each stage bears the same effort:

$$h^N = H$$

$$h = \sqrt[N]{H}$$

Stage efforts: $g_1 f_1 = g_2 f_2 = \dots = g_N f_N$

Effective fanout of each stage: $f_i = h/g_i$

Minimum path delay

$$\hat{D} = \sum (g_i f_i + p_i) = NH^{1/N} + P$$

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Optimal Number of Stages

For a given load,
and given input capacitance of the first gate
Find optimal number of stages and optimal sizing

$$D = NH^{1/N} + Np_{inv}$$

$$\frac{\partial D}{\partial N} = -H^{1/N} \ln(H^{1/N}) + H^{1/N} + p_{inv} = 0$$

Substitute 'best stage effort' $h = H^{1/N}$

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Logical Effort

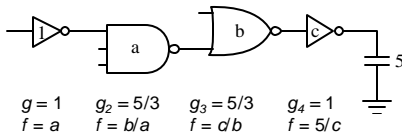
Gate Type	Number of Inputs			
	1	2	3	n
Inverter	1			
NAND		4f	5f	(n+2)f
NOR		5f	7f	(2n+1)f
Multiplexer		2	2	2
XOR		4	12	

From Sutherland, Sproull

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Example: Optimize Path



Effective fanout, $F =$

$G =$

$H =$

$h =$

$a =$

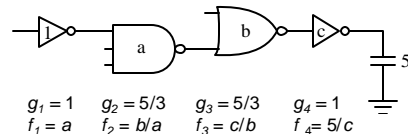
$b =$

$c =$

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Example: Optimize Path



Effective fanout, $F = 5$

$G = 25/9$

$H = 125/9 = 13.9$

$h = 1.93$

$a = h/g_2 = 1.16$

$b = ha/g_3 = 1.34$

$c = hb/g_4 = 2.59$

(since no branching here then $B=1$, $H=GFB$)
(this is the optimum effort for each gate $h=H^{1/4}$)
(from $h=f_1g_2=1.93$ and $f_1=a$)
(same as $h=f_2g_3=1.93$ and $f_2=b/a$)
(same as $h=f_3g_4=1.93$ and $f_3=c/b$)

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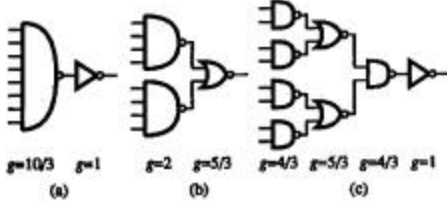
Example - 8-input AND

Intrinsic delays

8+1

4+2

2+2+2+1



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Fan out is not known here



Method of Logical Effort

- Compute the path effort: $H = GBF$
- Find the best number of stages $N \sim \log_4 H$
- Compute the stage effort $h = H^{1/N}$
- Sketch the path with this number of stages
- Work either from either end, find sizes:
 $C_{in} = C_{out} * g/h$

Reference: Sutherland, Sproull, Harris, "Logical Effort, Morgan-Kaufmann 1999.

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Summary

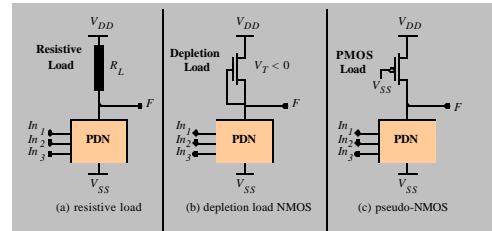
Table 4: Key Definitions of Logical Effort

Term	Stage expression	Path expression
Logical effort	g (see Table 1)	$G = \prod g_i$
Electrical effort	$h = \frac{C_{out}}{C_{in}}$	$H = \frac{C_{out}(path)}{C_{in}(path)}$
Branching effort	n/a	$B = \prod b_i$
Effort	$f = gh$	$F = GBH$
Effort delay	f	$D_F = \sum f_i$
Number of stages	f	N
Parasitic delay	p (see Table 2)	$P = \sum p_i$
Delay	$d = f + p$	$D = D_F + P$

Sutherland, Sproul, Harris

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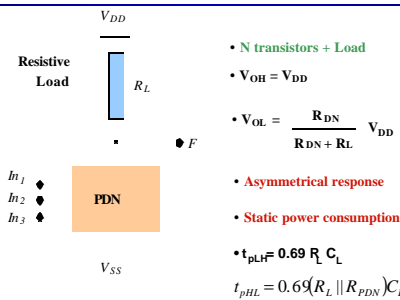
Ratio Based Logic



Goal: to reduce the number of devices over complementary CMOS

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Ratio Based Logic



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Ratio Based Logic Problems

Problems with Resistive Load

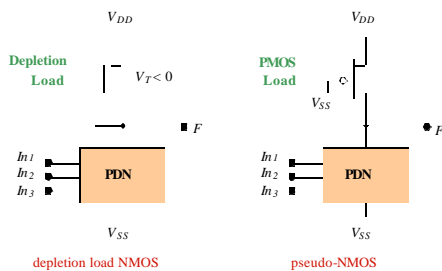
- $I_L = (V_{DD} - V_{out}) / R_L$
- Charging current drops rapidly once V_{out} starts to rise

Solution: Use a current source!

- Available current is independent of voltage
- Reduces t_{pLH} by 25%

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Active Loads



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Active Loads

Depletion mode NMOS load

- $V_{GS} = 0$
- $I_L \sim (k_n \text{load} / 2) (|V_{Tn}|)^2$
- Deviates from ideal current source
 - Channel length modulation
 - Body effect
 - $V_{SB} \neq V_{DD}$
 - varies with V_{out}
 - reduces $|V_{Tn}|$, hence I_L gets smaller for increasing V_{out}

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Active Loads

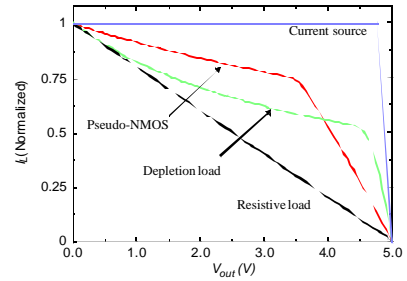
Pseudo-NMOS load

- No body effect, $V_{SB} = 0V$
- $V_{GS} = -V_{DD}$, higher load current
- $I_L = (k_p / 2) (V_{DD} - |V_{Tn}|)^2$
- Larger V_{GS} causes pseudo-NMOS load to leave saturation mode sooner than NMOS

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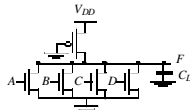
Load Lines of Ratioed Gates



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Pseudo-NMOS



$V_{OH} = V_{DD}$ (similar to complementary CMOS)

$$k_p \left((V_{DD} - V_{Tn}) V_{OL} - \frac{V_{OL}^2}{2} \right) = \frac{k_n}{2} V_{DD} - |V_{Tp}|^2$$

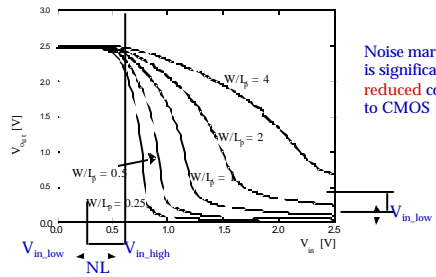
$$V_{OL} = (V_{DD} - V_{Tn}) \left[1 - \sqrt{1 - \frac{k_p}{k_n}} \right] \text{ (assuming that } V_T = V_{Tn} = |V_{Tp}| \text{)}$$

SMALLER AREA & LOAD BUT STATIC POWER DISSIPATION!!!

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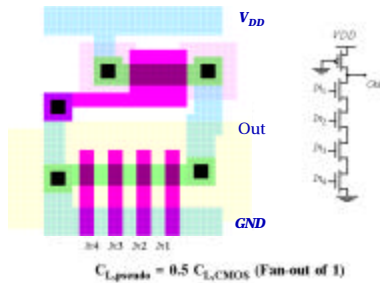
Pseudo-NMOS VTC



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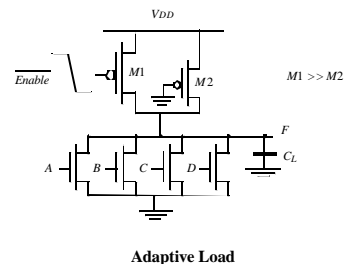
Pseudo-NMOS NAND Gate



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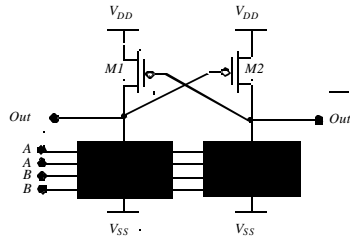
Improved Loads



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Improved Loads (2)

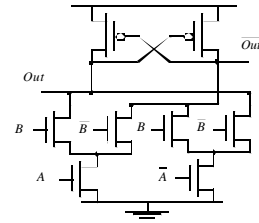


Differential Cascode Voltage Switch Logic (DCVSL)

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DCVSL Example

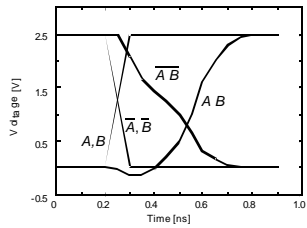


XOR-NXOR gate

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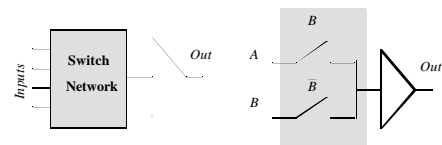
DCVSL Transient Response



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Pass-Transistor Logic

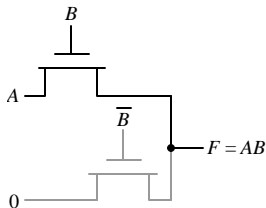


- N transistors
- No static consumption

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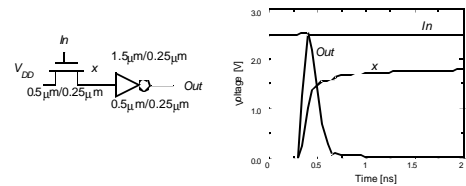
Example: AND Gate



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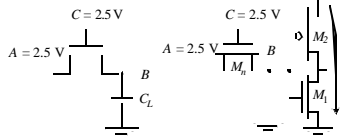
NMOS-Only Logic



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NMOS-only Switch



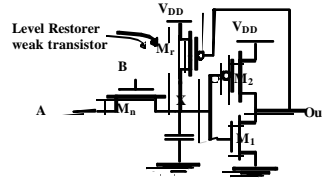
V_B does not pull up to 2.5V, but $2.5V - V_{TN}$

Threshold voltage loss causes static power consumption

NMOS has higher threshold than PMOS (body effect)

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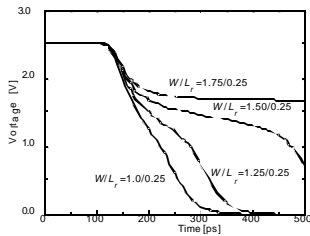
NMOS Only Logic: Level Restoring Transistor



- Advantages: Full Swing, No static power dissipation
- Restorer adds capacitance, takes away pull down current at X
- Ratio problem

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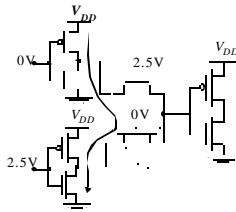
Restorer Sizing



- Upper limit on restorer size
- Pass-transistor pull-down can have several transistors in stack

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Solution 2: Single Transistor Pass Gate with $V_T=0$

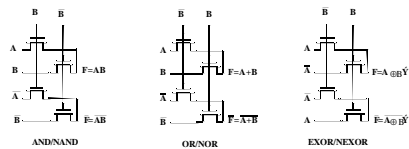
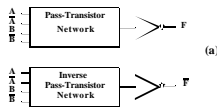


If pass transistors have $V_T=0$ the output Does not require level restorer but there is a leakage current

WATCH OUT FOR LEAKAGE CURRENTS

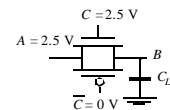
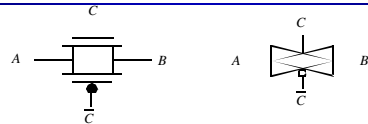
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Complementary Pass Transistor Logic



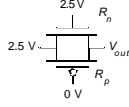
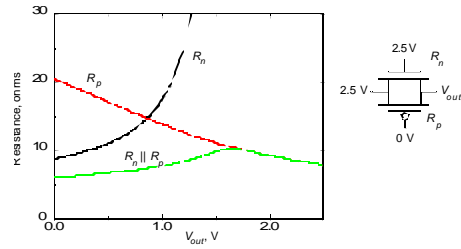
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Solution 3: Transmission Gate



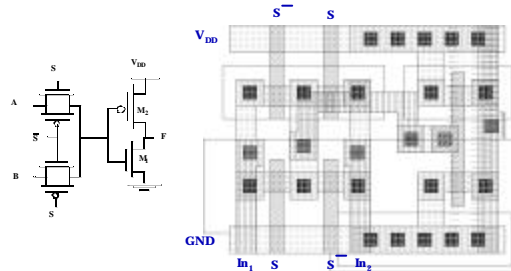
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Resistance of Transmission Gate



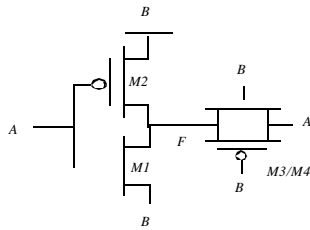
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Pass-Transistor Based Multiplexer



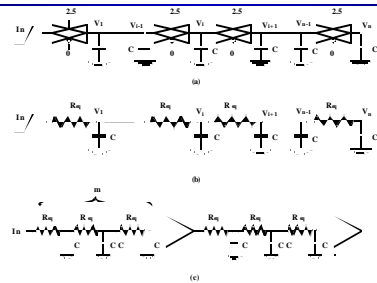
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Transmission Gate XOR



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Delay in Transmission Gate Networks



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Delay Optimization

• Delay of RC chain

$$t_p = 0.69 \sum_{k=0}^n C_k R_{eq,k} \approx 0.69 C_{eq} \frac{n(n+1)}{2}$$

• Delay of Buffered Chain

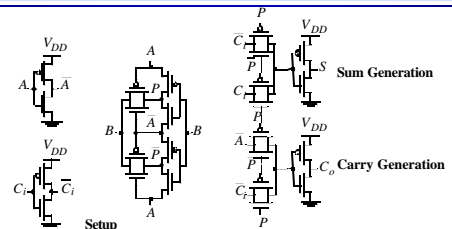
$$t_p = 0.69 \left[\frac{2}{n} C_{eq} R_{eq} \frac{n(n+1)}{2} \right] + \left(\frac{n}{n-1} \right) t_{buf}$$

$$= 0.69 \left[C_{eq} \frac{n(n+1)}{2} \right] + \left(\frac{n}{n-1} \right) t_{buf}$$

$$n_{opt} = 1.7 \sqrt{\frac{t_{buf}}{C_{eq} R_{eq}}}$$

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Transmission Gate Full Adder



Similar delays for sum and carry

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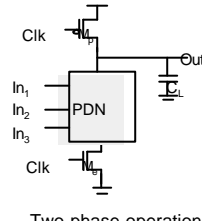
Dynamic CMOS

- In **static** circuits at every point in time (except when switching) the output is connected to either GND or V_{DD} via a low resistance path.
 - » fan-in of n requires $2n$ (n N-type + n P-type) devices
- **Dynamic** circuits rely on the temporary storage of signal values on the capacitance of high impedance nodes.
 - » requires on $n + 2$ ($n+1$ N-type + 1 P-type) transistors

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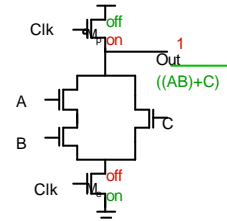


Dynamic Gate



Two phase operation
Precharge (Clk = 0)
Evaluate (Clk = 1)

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Conditions on Output

- Once the output of a dynamic gate is discharged, it cannot be charged again until the next precharge operation.
- Inputs to the gate can make **at most one** transition during evaluation.
- Output can be in the high impedance state during and after evaluation (PDN off), state is stored on C_L

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Properties of Dynamic Gates

- Logic function is implemented by the PDN only
 - » number of transistors is $N + 2$ (versus $2N$ for static complementary CMOS)
- Full swing outputs ($V_{OL} = \text{GND}$ and $V_{OH} = V_{DD}$)
- Non-ratioed - sizing of the devices does not affect the logic levels
- Faster switching speeds
 - » reduced load capacitance due to **lower input** capacitance (C_{in})
 - » reduced load capacitance due to smaller output loading (C_{out})
 - » no I_{sc} , so all the current provided by PDN goes into discharging C_L

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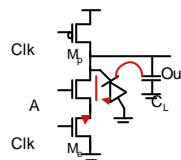
Properties of Dynamic Gates

- Overall power dissipation usually **higher** than static CMOS
 - » no static current path ever exists between V_{DD} and GND (including P_{sc})
 - » no glitching
 - » **higher transition probabilities**
 - » extra load on Clk
- PDN starts to work as soon as the input signals exceed V_{Tn} , so V_{Mp} , V_{IH} and V_{IL} equal to V_{Tn}
 - » low noise margin (NM_L)
- Needs a precharge/evaluate clock

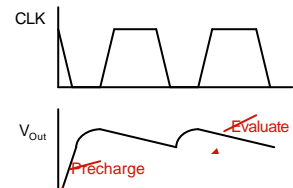
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Issues in Dynamic Design 1: Charge Leakage



Leakage sources

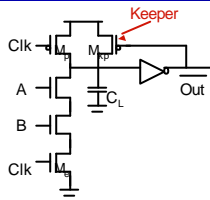


Dominant component is subthreshold current

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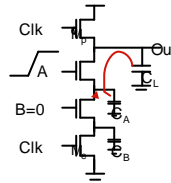
Solution to Charge Leakage



Same approach as level restorer for pass-transistor logic

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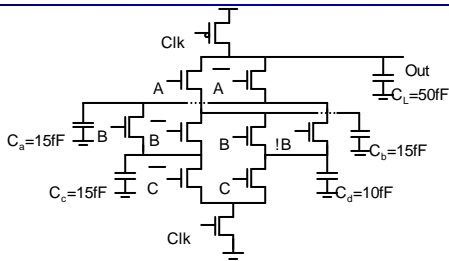
Issues in Dynamic Design 2: Charge Sharing



Charge stored originally on C_L is redistributed (shared) over C_L and C_A leading to reduced robustness

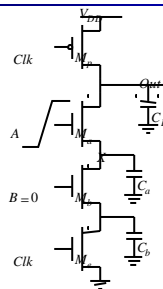
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Charge Sharing Example



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Charge Sharing



case 1) if $\Delta V_{out} < V_{Tn}$

$$C_L V_{DD} = C_L V_{out}(t) + C_a (V_{DD} - V_{Tn}(V_X))$$

or

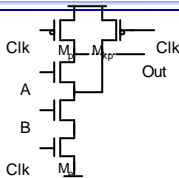
$$\Delta V_{out} = V_{out}(t) - V_{DD} = -\frac{C_a}{C_L} (V_{DD} - V_{Tn}(V_X))$$

case 2) if $\Delta V_{out} > V_{Tn}$

$$\Delta V_{out} = -V_{DD} \left(\frac{C_a}{C_a + C_L} \right)$$

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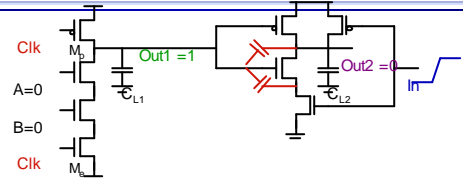
Solution to Charge Redistribution



Precharge internal nodes using a clock-driven transistor (at the cost of increased area and power)

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Issues in Dynamic Design 3: Backgate Coupling



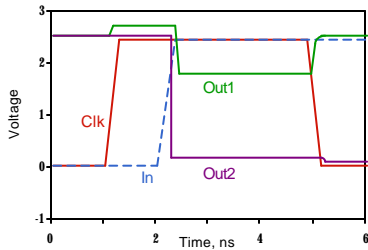
Dynamic NAND

Static NAND

Output connected to a NAND gate and Out2 pulls down Out1 through capacitive coupling

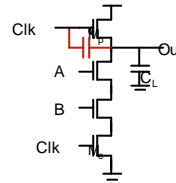
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Backgate Coupling Effect



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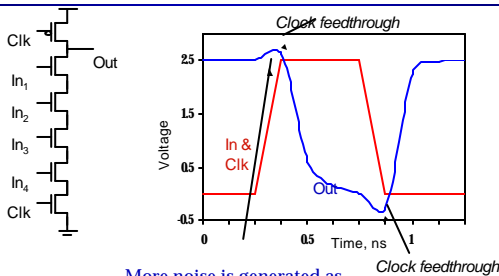
Issues in Dynamic Design 4: Clock Feedthrough



Coupling between Out and Clk input of the precharge device due to the gate to drain capacitance. So voltage of Out can rise above V_{DD} . The fast rising (and falling edges) of the clock couple to Out.

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Clock Feedthrough



More noise is generated as a result of clock coupling

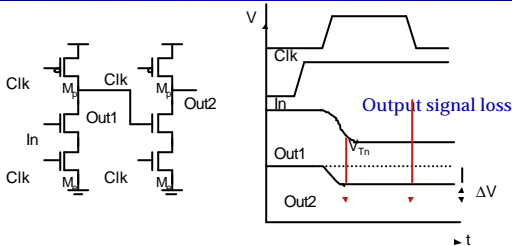
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Other Effects

- Capacitive coupling between output wires pulls down prestored charges
- Substrate coupling
- Minority charge injection
- Supply noise (negative ground bounce may discharge the output)

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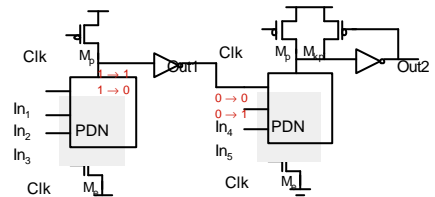
Cascading Dynamic Gates



Only 0 → 1 transitions allowed at inputs!
So do not connect these gates directly

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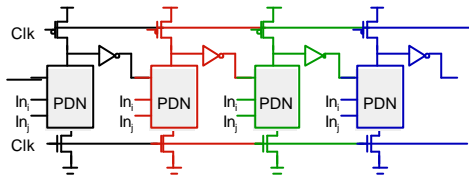
Domino Logic



Here we guarantee proper 0 to 1 transitions between gates

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Why Domino?



Like falling dominos!

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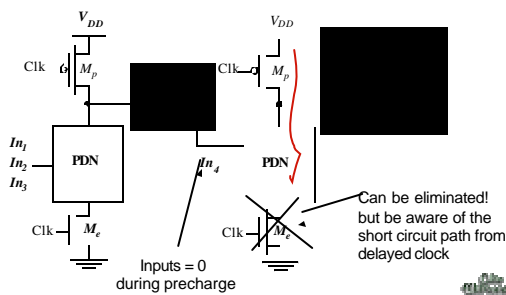
Properties of Domino Logic

- Only non-inverting logic can be implemented
- Very high speed
 - » static inverter can be skewed, only L-H transition so make PMOS of inverter stronger
 - » Input capacitance reduced – smaller logical effort

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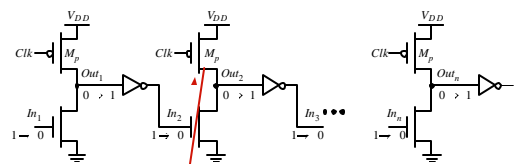
Designing with Domino Logic



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Footless Domino

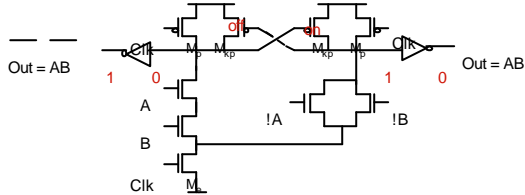


The first gate in the chain needs a foot switch
Precharge is rippling – short-circuit current
A solution is to **delay** the clock for each stage

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Differential (Dual Rail) Domino

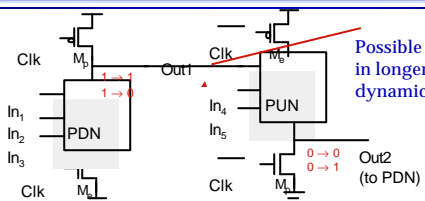


Solves the problem of non-inverting logic

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np-CMOS

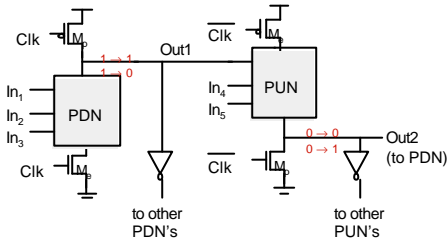


Only 0 → 1 transitions allowed at inputs of PUN
Only 1 → 0 transitions allowed at inputs of PDN

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NORA Logic

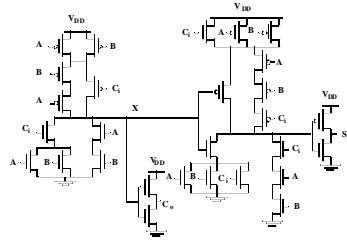


WARNING: Very sensitive to noise!

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Example: Full Adder



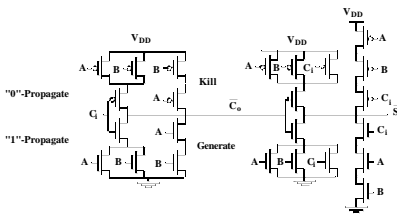
$$C_o = AB + C_i(A+B)$$

28 transistors

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A Revised Adder Circuit



24 transistors

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